



Product Change Notification / JAON-30NGXA111

Date:

17-Nov-2020

Product Category:

Interface- Controller Area Network (CAN), Interface- LIN Transceiver

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4036 and 4036.001 Final Notice: Qualification of MTAI as an additional assembly site for selected Atmel ATA656x, ATA6570, ATA6625, ATA663211 and ATA663254 device families available in 8L and 14L SOIC packages.

Affected CPNs:

[JAON-30NGXA111_Affected_CPN_11172020.pdf](#)

[JAON-30NGXA111_Affected_CPN_11172020.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly site for selected Atmel ATA656x, ATA6570, ATA6625, ATA663211 and ATA663254 device families available in 8L and 14L SOIC packages.

Pre Change:

For 14L SOIC package: Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material with NiPd-AgPd lead plating. For 8L SOIC package: Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material with NiPdAu lead plating.

Post Change:

For 14L SOIC package: Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material with NiPd-AgPd lead plating or assembled at MTAI using 8390A die attach and G600V mold compound material with Matte Tin lead plating
For 8L SOIC package: Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material with NiPdAu lead plating or assembled at MTAI using 8390A die attach and G600V mold compound material with Matte Tin lead plating

Pre and Post Change Summary:For 14L SOIC Package:

	Pre Change	Post Change	
Assembly Site	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	EN-4900GC	EN-4900GC	8390A
Molding compound material	G700	G700	G600V
Lead frame material	CDA194	CDA194	CDA194
Lead Plating	NiPd-AgPd	NiPd-AgPd	Matte Tin

For 8L SOIC Package:

	Pre Change	Post Change	
Assembly Site	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	8290	8290	8390A
Molding compound material	G700	G700	G600V
Lead frame material	CDA194	CDA194	CDA194
Lead Plating	NiPdAu	NiPdAu	Matte Tin

Impacts to Data Sheet: None.**Change Impact:**None.**Reason for Change:**To improve on-time delivery performance by qualifying MTAI as an additional assembly site.**Change Implementation Status:**In Progress**Estimated First Ship Date:**December 17, 2020 (date code: 2051)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2020					->	November 2020				December 2020				
Workweek	01	02	03	04	05		45	46	47	48	49	50	51	52	53
Initial PCN Issue Date					X										
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated First Ship Date													X		

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: **January 31, 2020:** Issued initial notification. **November 17, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on December 17, 2020. Corrected lead finish at ANAP from NiPd-AgPd to NiPdAu.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-30NGXA111_Qual_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATA663211-GAQW
ATA663254-GAQW
ATA663254-GAQW-VAO
ATA6562-GAQW0
ATA6566-GAQW0
ATA6563-GAQW0
ATA6564-GAQW0
ATA6562-GAQW1
ATA6561-GAQW
ATA6560-GAQW
ATA6564-GAQW1
ATA6563-GAQW1
ATA6566-GAQW1
ATA6560-GAQW-N
ATA6561-GAQW-N
ATA6560-GAQW-VAO
ATA6625-GAQW
ATA6570-GNQW0
ATA6570-GNQW1